Material and Quality Overview
Microelectronics Packaging Facilities

- **500m² Packaging facilities to support R&D**

Assembly Facilities:

- Wafer Backgrinder (100um thickness)
- Stencil print wafer bumping (150um pitch)
- Die attach and wirebonding (Au, Cu, Pd at 35um pitch)
- Different Flip Chip bonding (+/- 3um, 500°C, 8 Kg bond force)
- Underfilling, NCP, dam & fill
- SMT and reflow

Developing RDL, TSV infrastructure

Material and Quality Overview
Microelectronics Packaging Facilities

Materials Characterization Facilities :

- Tensile, compression, fracture mechanics with bulk material testing
- Thermal analysis for metal, polymer & composite.
- Macroscopic and Microscopic analysis with elemental analysis
- Interfacial and interconnect characterization

Reliability Facilities :

- Moisture Sensitive Testing
- Thermal shock
- Temperature cycling
- Autoclave
- Thermal storage
- X-section analysis